Ablebond 958-11

Epoxy; Epoxide

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Message:

ABLEBOND® 958-11 adhesive is designed to absorb stresses produced when bonding large ICs.
ABLEBOND® 958-11 meets the requirements of MIL-STD-883, Method 5011.

General Information			
Features	Shock Absorbent		
Uses	Adhesives		
Agency Ratings	MIL Std. 883 Method 5011		
Appearance	White		
Forms	Paste		
Physical	**Nominal Value**		
pH	4.0 to 9.0		
Ionic Chloride	< 300	ppm	
Ionic Potassium	< 50.0		
Ionic Sodium	< 50.0		
Lap Shear - Aluminum (25°C)	> 18.6	MPa	
Shear Strength - Die (Gold) [1] (25°C)	> 25	N	
Water Extract Conductivity	43.0	µS/cm	
Weight Loss on Heating (200°C)	< 1.0	%	
Thermal	**Nominal Value**	**Unit**	**Test Method**
Glass Transition Temperature	89.0	°C	DSC
CLTE - Flow			
< 89°C	1.5E-5	cm/cm/°C	
> 89°C	4.5E-5	cm/cm/°C	
Electrical	**Nominal Value**	**Unit**	**Test Method**
Volume Resistivity	5.0E+14	ohms·cm	ASTM D257
Thermoset	**Nominal Value**	**Unit**	
Pot Life (25°C)	20000	min	
Shelf Life (-40°C)	52	wk	
Thermoset Mix Viscosity (25°C)	40000 to 50000	cP	
Post Cure Time			
130°C	2.0	hr	
150°C	1.0	hr	
NOTE			
1.	2 X 2 mm Ceramic		